



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
-20V	$80m\Omega$ @ $V_{GS} = 4.5V$	-2.7A
	110mΩ @ V _{GS} = 2.5V	-2.1A

Description

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

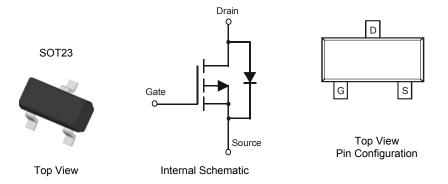
- Backlighting
- Power Management Functions
- DC-DC Converters
- Motor control

Features

- Low On-Resistance
- Low Input Capacitance
- · Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 [®]
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (approximate)



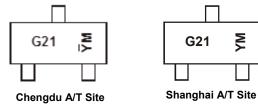
Ordering Information (Note 4)

Ī	Part Number	Case	Packaging
	DMG2301U-7	SOT23	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



G21 = Product Type Marking Code YM = Date Code Marking for SAT (Shanghai Assembly/ Test site) $\overline{Y}M$ = Date Code Marking for CAT (Chengdu Assembly/ Test site) Y or \overline{Y} = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	2009	2010	20	11	2012	2013	2014	2015	20	16	2017	2018
Code	W	Х)	1	Z	Α	В	С		D	Е	F
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V_{DSS}	-20	V	
Gate-Source Voltage		V _{GSS}	±8	V	
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	lD	-2.7 -2.1	А
Continuous Drain Current (Note 5) V _{GS} = -2.5V	Steady State	I _D	-2.1 -1.7	Α	
Pulsed Drain Current (Note 6)		I _{DM}	-27	Α	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	0.8	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	$R_{ heta JA}$	157	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

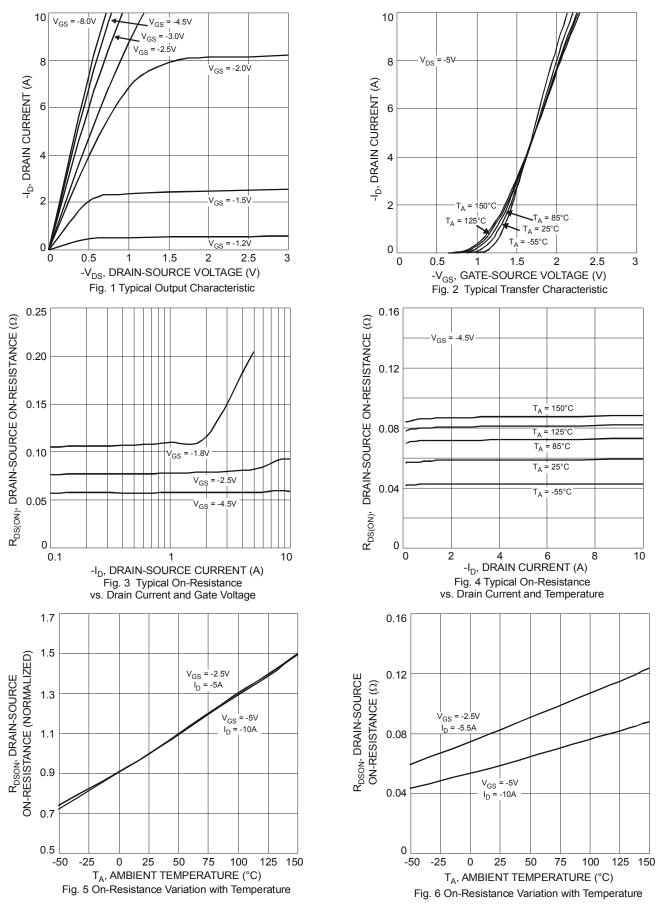
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1.0	μΑ	$V_{DS} = -16V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	-0.45	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance	J			80	mΩ	$V_{GS} = -4.5V$, $I_{D} = -2.8A$
Static Drain-Source On-Resistance	R _{DS (ON)}	_	_	110	mtz	$V_{GS} = -2.5V$, $I_{D} = -2.0A$
Forward Transfer Admittance	Y _{fs}	_	10	_	S	$V_{DS} = -5V$, $I_{D} = -2.8A$
Diode Forward Voltage	V_{SD}	_	-0.75	-1.0	V	$V_{GS} = 0V, I_{S} = -1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	608	_	pF	., ., ., .,
Output Capacitance	Coss	_	82	_	pF	$V_{DS} = -6V, V_{GS} = 0V$ - f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	72	_	pF	1 - 1:0WH 12
Gate Resistance	R_G	_	44.9	_	Ω	$V_{GS} = 0V, V_{DS} = 0V, f = 1.0MHz$
Total Gate Charge	Q_g	_	6.5	_	nC	
Gate-Source Charge	Q_{gs}	_	0.9	_	nC	$V_{GS} = -4.5V$, $V_{DS} = -10V$, $I_{D} = -3A$
Gate-Drain Charge	Q_{gd}	_	1.5	_	nC	
Turn-On Delay Time	t _{D(on)}	_	12.5	40	ns	
Turn-On Rise Time	t _r	_	10.3	30	ns	$V_{DS} = -10V, V_{GS} = -4.5V,$
Turn-Off Delay Time	t _{D(off)}		46.5	140	ns	$R_L = 10\Omega$, $R_G = 1.0\Omega$, $I_D = -1A$
Turn-Off Fall Time	t _f		22.2	66	ns	

Notes:

- 5. Device mounted on FR-4 PCB with minimum recommended pad layout.
- Severe thinds do not have a severe the severe the







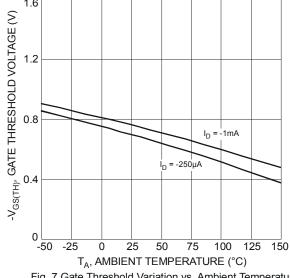
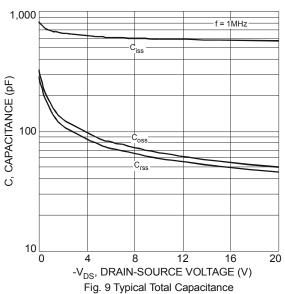
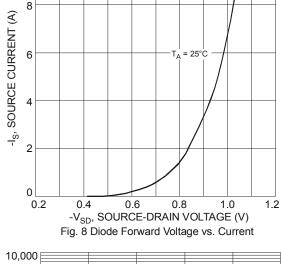


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





10

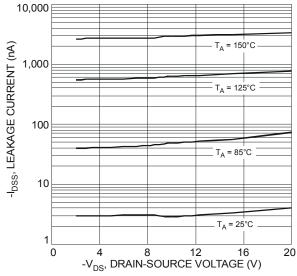
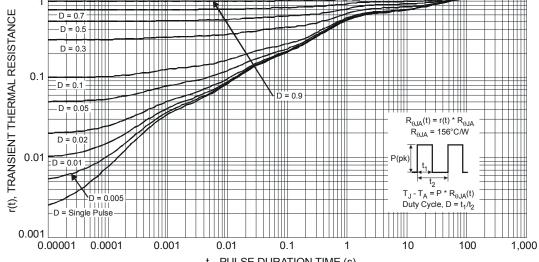


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

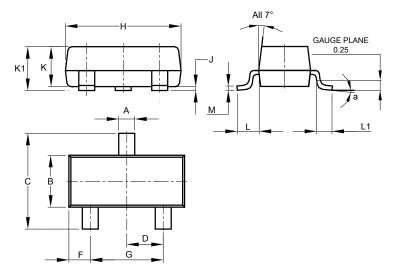


t₁, PULSE DURATION TIME (s) Fig. 11 Transient Thermal Response



Package Outline Dimensions

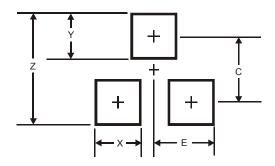
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23								
Dim	Min	Max	Тур					
Α	0.37	0.51	0.40					
В	1.20	1.40	1.30					
С	2.30	2.50	2.40					
D	0.89	1.03	0.915					
F	0.45	0.60	0.535					
G	1.78	2.05	1.83					
Н	2.80	3.00	2.90					
J	0.013	0.10	0.05					
K	0.890	1.00	0.975					
K1	0.903	1.10	1.025					
L	0.45	0.61	0.55					
L1	0.25	0.55	0.40					
М	0.085	0.110						
α	8°							
All	All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
E	1.35



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